DSC7101

Silicon NPN epitaxial planar type

For low frequency amplification Complementary to DSA7101

■ Features

- \bullet Low collector-emitter saturation voltage $V_{\text{CE(sat)}}$
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

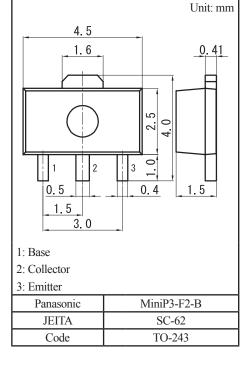
■ Marking Symbol: 5C

Packaging

 $DSC7101\times 0L \quad Embossed \ type \ (Thermo-compression \ sealing): 1000 \ pcs \ / \ reel \ (standard)$

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V _{CBO}	80	V
Collector-emitter voltage (Base open)	V _{CEO}	80	V
Emitter-base voltage (Collector open)	V _{EBO}	5	V
Collector current	$I_{\rm C}$	0.5	A
Peak collector current	I _{CP}	1	A
Collector power dissipation	P _C	1	W
Junction temperature	T _j	150	°C
Operating ambient temperature	T _{opr}	-40 to +85	°C
Storage temperature	T _{stg}	-55 to +150	°C



Note) Printed circuit board: Copper foil area of $1~\rm cm^2$ or more, and the board thickness of $1.7~\rm mm$ for the collector portion

Absolute maximum rating without heat sink for P_C is $\ 0.5 \ W$

■ Electrical Characteristics $T_a = 25$ °C±3°C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_C = 10 \mu A, I_E = 0$	80			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_C = 100 \mu A, I_B = 0$	80			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 10 \mu A, I_C = 0$	5			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 20 \text{ V}, I_{E} = 0$			0.1	μΑ
Forward current transfer ratio *1	h _{FE1} *2	$V_{CE} = 10 \text{ V}, I_{C} = 150 \text{ mA}$	130		330	
	h _{FE2}	$V_{CE} = 5 \text{ V}, I_{C} = 500 \text{ mA}$	50			_
Collector-emitter saturation voltage *1	V _{CE(sat)}	$I_C = 300 \text{ mA}, I_B = 30 \text{ mA}$		0.15	0.4	V
Base-emitter saturation voltage *1	V _{BE(sat)}	$I_C = 300 \text{ mA}, I_B = 30 \text{ mA}$		0.85	1.2	V
Transition frequency	f_T	$V_{CE} = 10 \text{ V}, I_{C} = 50 \text{ mA}$		150		MHz
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		7	20	pF

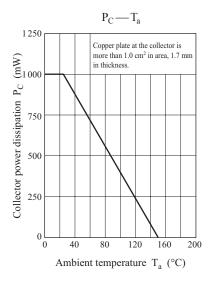
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

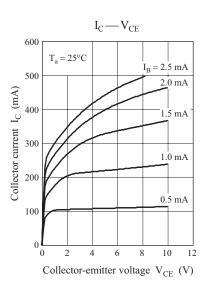
2. *1: Pulse measurement

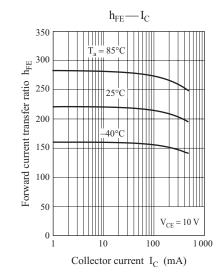
*2: Rank classification

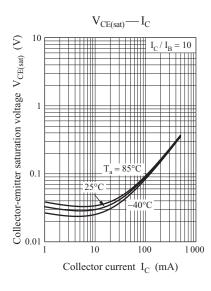
Code	R	S	0
Rank	R	S	No-rank
h_{FE1}	130 to 220	185 to 330	130 to 330
Marking Symbol	5CR	5CS	5C

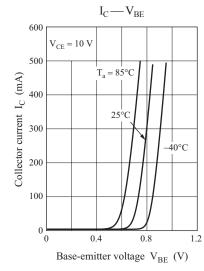
Product of no-rank is not classified and have no marking symbol for rank.

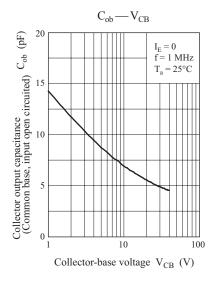


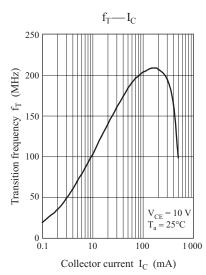








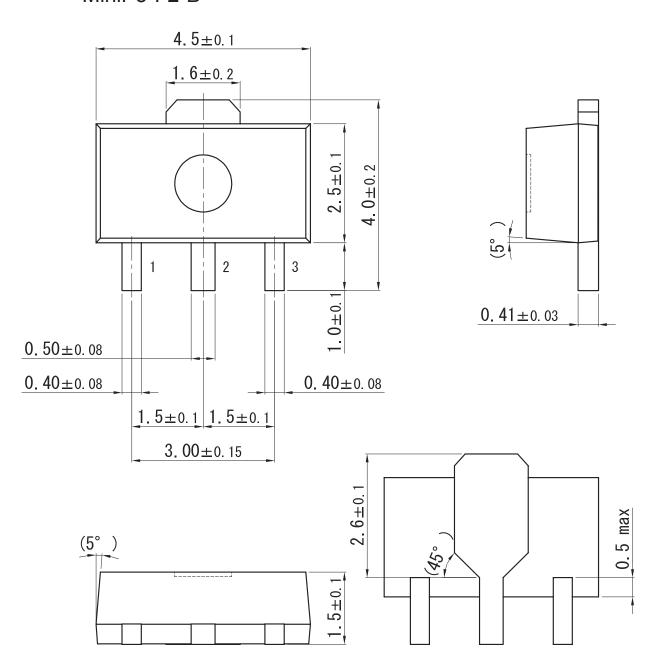




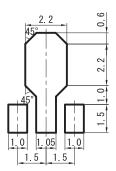
Ver. DED 2

MiniP3-F2-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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